

SOT862-1

plastic low profile fine-pitch ball grid array package; 336 balls; body 12 x 12 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA336
Package type industry code	LFBGA336
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-7-2004

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		[tbd]	-	1.5	1.5	mm
A ₂	package height		0.95	-	1.05	1.2	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	336	-	



2. Package outline

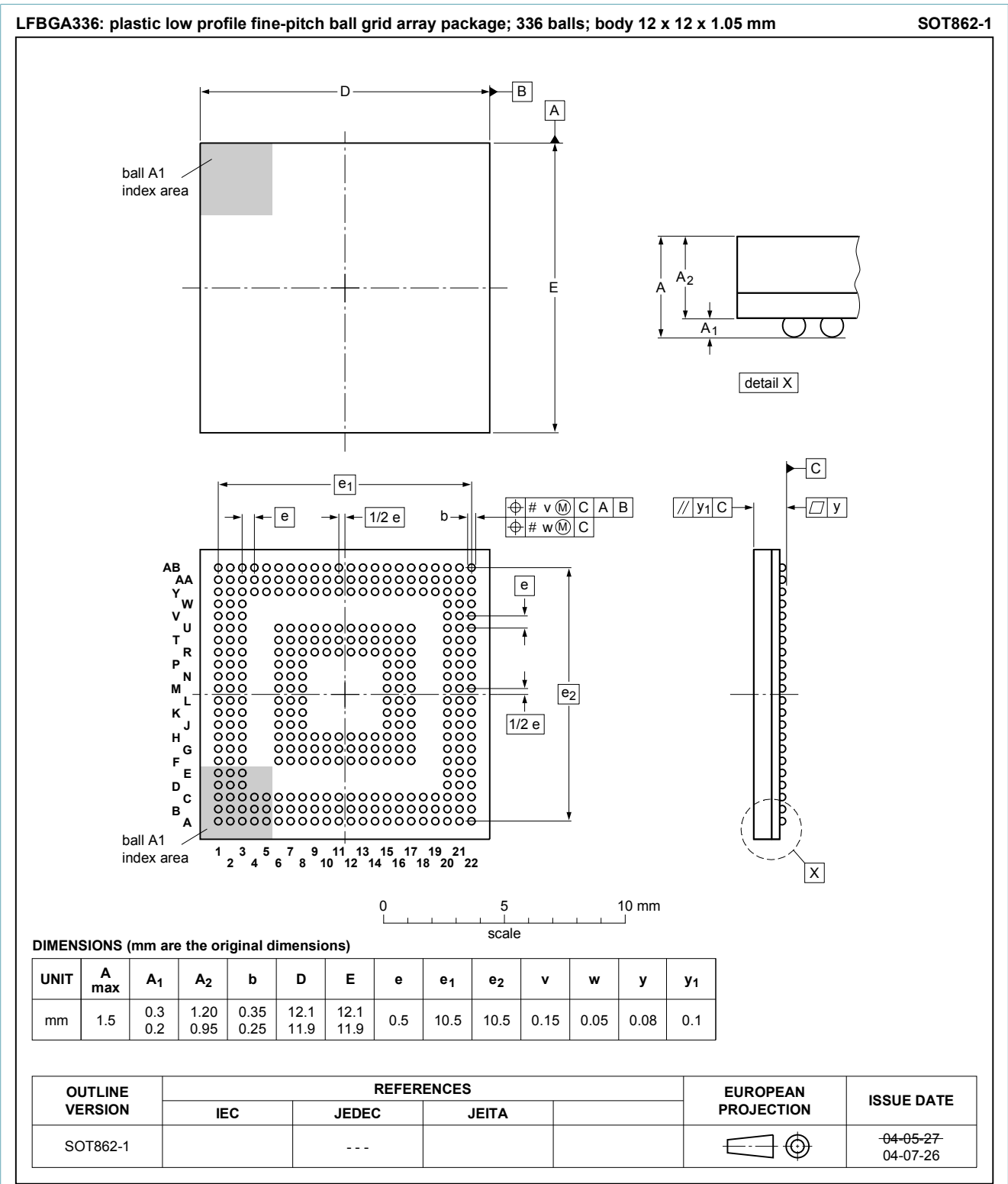
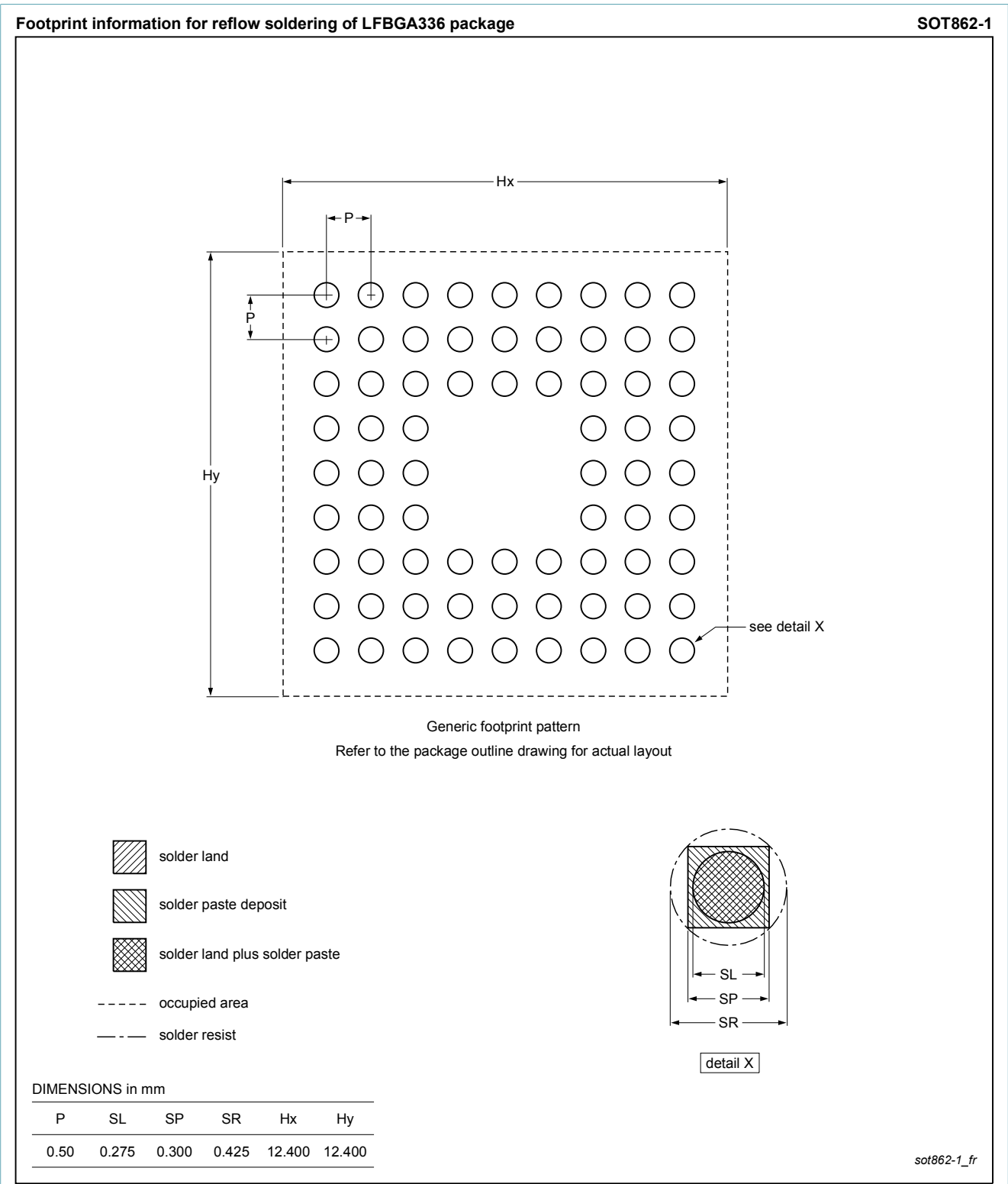


Fig. 1. Package outline LFBGA336 (SOT862-1)

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3. Soldering



4. Legal information

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